

Title (en)  
COMPOSITE ELECTRICAL CONDUCTOR AND METHOD FOR PRODUCING IT

Title (de)  
ELEKTRISCHER VERBUNDLEITER UND HERSTELLVERFAHREN DAFÜR

Title (fr)  
CONDUCTEUR ELECTRIQUE COMPOSITE ET PROCEDE POUR SA FABRICATION

Publication  
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Application  
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Abstract (en)  
[origin: WO2007071355A1] The invention, and consequently the composite conductor, comprises a base alloy of CuAg, with an Ag fraction of 0.08 to 0.12%, and an alloy of CuMg, present at the edge (14) or at the core (20, 22) in the cross section of the composite conductor, with an Mg fraction of 0.1 to 0.7%. A contact wire 10 (grooved contact wire or trolley wire) is preferably proposed, containing a wire of CuMg 0.1...0.7 in the core 20 and surrounded by a casing of CuAg 0.1. The Holton Conform cladding process is proposed as a production method, described for example in EP 0 125 788 A2.

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